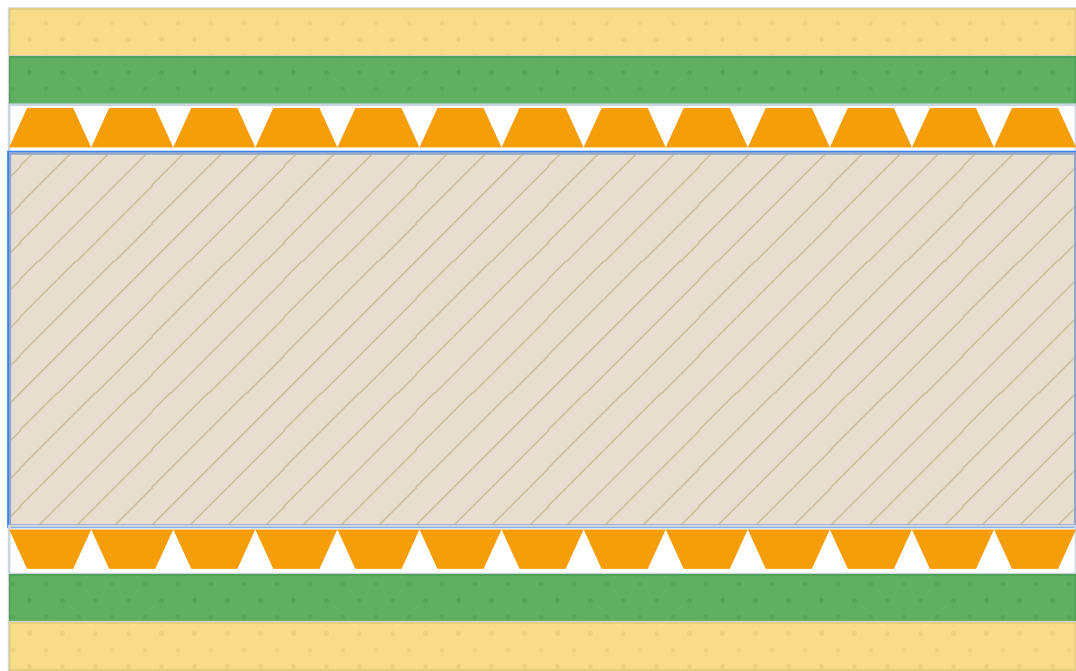


Top Surface Finish
 Top Solder Mask
L1

RO3035

L4
 Bottom Solder Mask
 Bottom Surface Finish



RO3035 2-Layer PCB

Spec	Type	Base Thickness	Processed Thickness	RC	DK
Immersion Tin		0.005			
		0.020			
	Signal	0.018	0.018		
Rogers	Core	0.127	0.127		3.55
	Signal	0.018	0.018		
		0.020			
Immersion Tin		0.005			

Thickness After Lamination: 0.163 mm

Finished PCB Thickness: 0.213 mm ±10%

Inner layer Residual copper ratio: